TSG-RAN Meeting #8   *RP-000296*
Düsseldorf, Germany, 21 - 23 June 2000

Agenda Item: **6**

Source: **CWTS**
To: **TSG-RAN #8**
Title: **Work Item Description "Low Chip Rate TDD UE Capability"**
Document for: **Approval**

Work Item Description

Title

Low chip rate TDD UE capability

1   3GPP Work Area

X	Radio Access
	Core Network
	Services

2   Linked work items

Low Chip Rate TDD physical layer
Low chip rate TDD Layer 2 and Layer 3 protocol aspects
Low chip rate TDD UTRAN architecture aspects
Smart Antenna
RF Radio Transmission/Reception, System Performance Requirements and Conformance Testing

3   Justification

The integration of TDD low chip rate option in Release 2000 is discussed and approved in RAN#6. The work plan of the integration of low chip rate TDD in R00 was discussed in RAN#7. As a feature, the low chip rate TDD is sub-divided into several building blocks via the email discussion. This paper is to describe one of the low chip rate TDD building block – UE capabilities.

4   Objective

The technical objective of this work item is complete the UE capabilities. And this work will affect the specifications for working group on UE capability.

−   For UE capability, it includes the following work tasks:
   −   Definition of UE capabilities for low chip rate option

Task	Planned Start	Planned Finish
Complete the TR for WG1	01/2000	05/2000
Drafting new specifications and CRs	06 /2000	12/2000

5   Service Aspects

None

6   MMI-Aspects

None

7   Charging Aspects

None

8   Security Aspects

None

9   Impacts

Affects:	USIM	ME	AN	CN	Others
Yes		X			
No	X		X	X	X
Don't know					

10   Expected Output and Time scale (to be updated at each plenary)

New specifications						
Spec No.	Title	Prime rsp. WG	2ndary rsp. WG(s)	Presented for information at plenary#	Approved at plenary#	Comments
Affected existing specifications						
Spec No.	CR	Subject			Approved at plenary#	Comments
25.926		UE Radio Access Capabilities			RAN #10	

11   Work item raporteurs

Mr. Daijun Zhang (CATT/CWTS) ?

12   Work item leadership

RAN WG2

13   Supporting Companies

14   Classification of the WI (if known)

	Feature (go to 14a)
X	Building Block (go to 14b)
	Work Task (go to 14c)

14a   The WI is a Feature: List of building blocks under this feature

(list of Work Items identified as building blocks)
The building blocks should be discussed and approved via email discussion

14b   The WI is a Building Block: parent Feature

(one Work Item identified as a feature)
   Low chip rate TDD

14c   The WI is a Work Task: parent Building Block

(one Work Item identified as a building block)